



SOT1571-8

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

6 September 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026 BBC
Mounting method type	S (surface mount)
Issue date	01-03-2018
Manufacturer package code	98ASA01155D

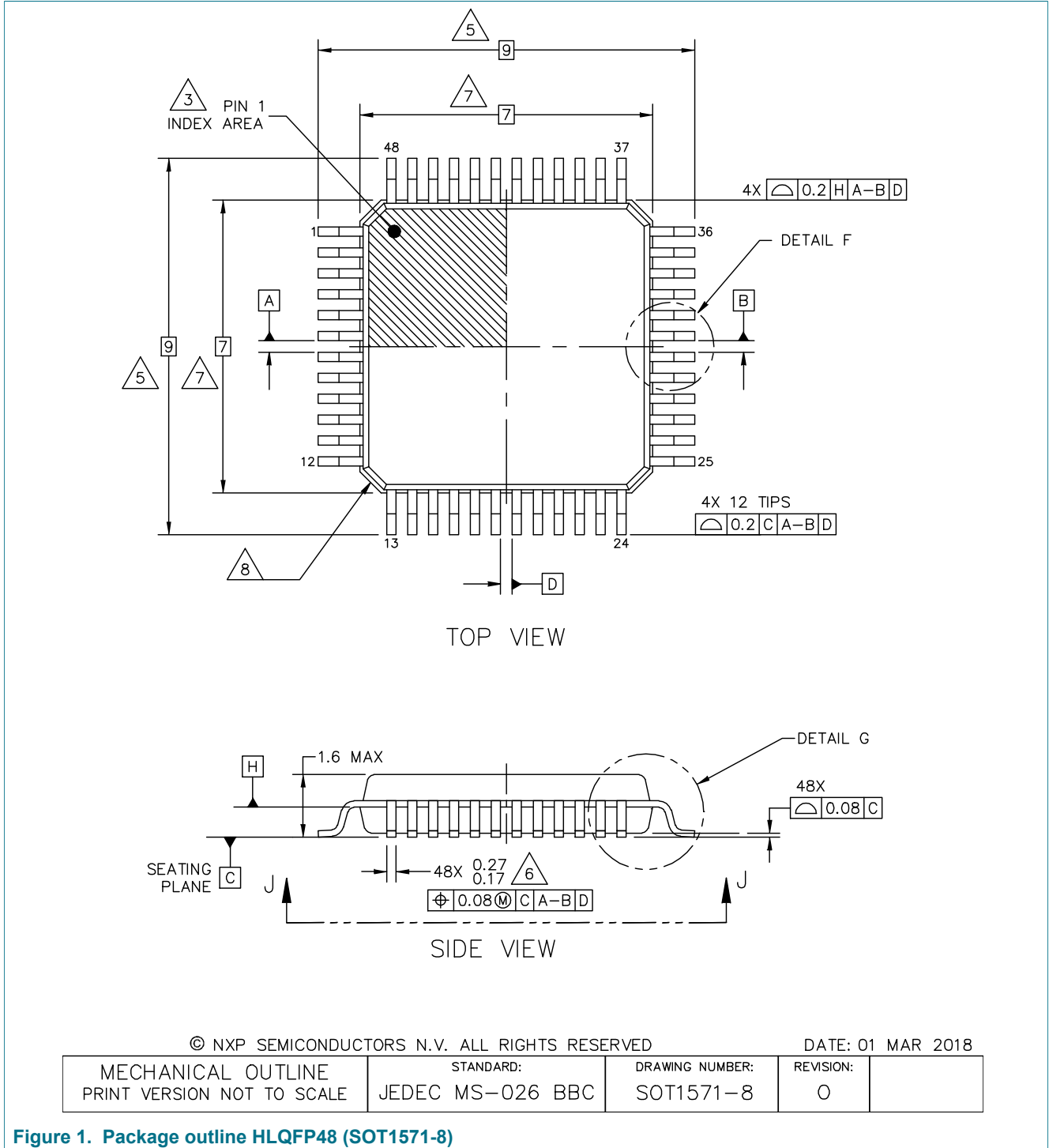
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline



HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

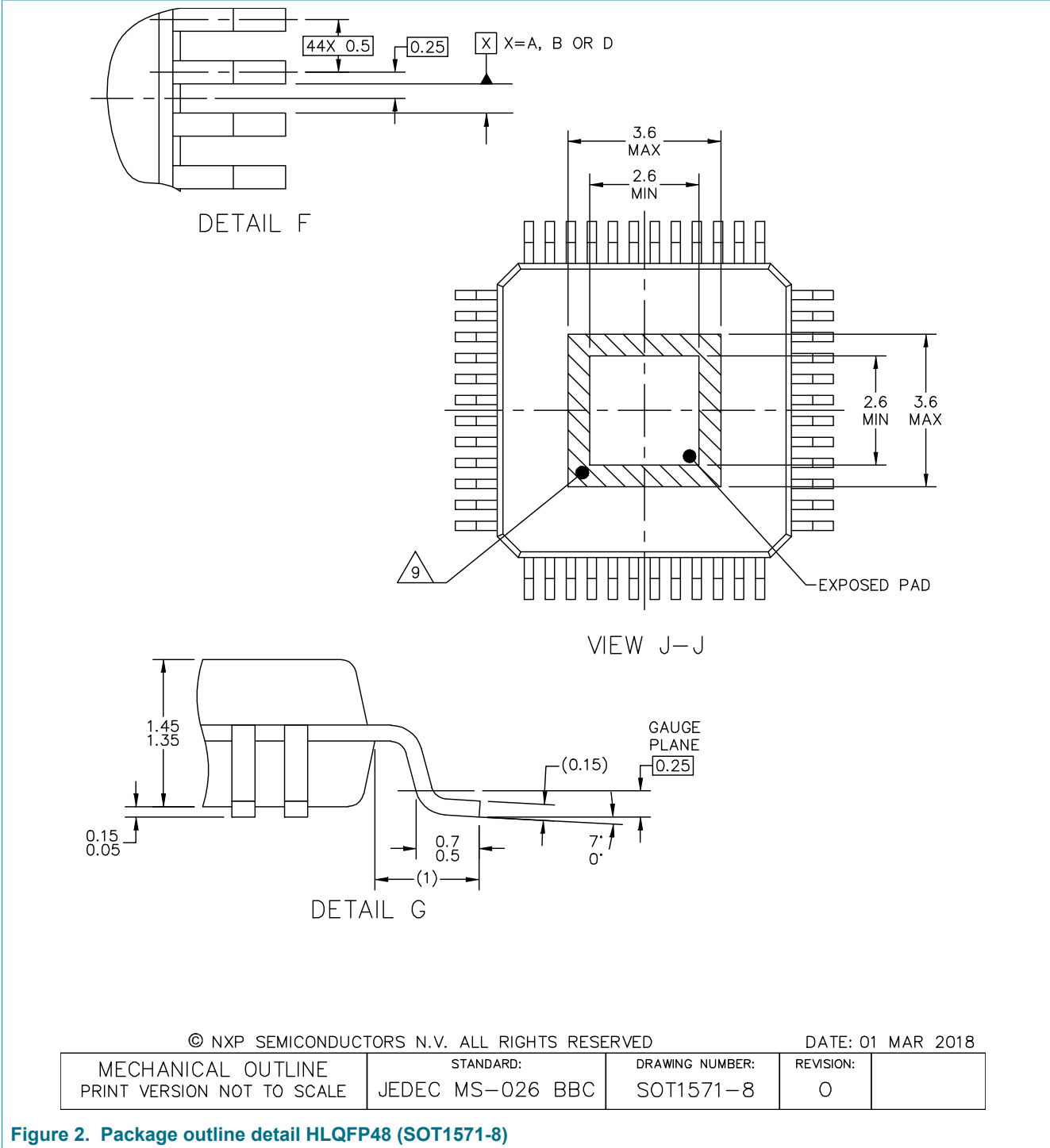
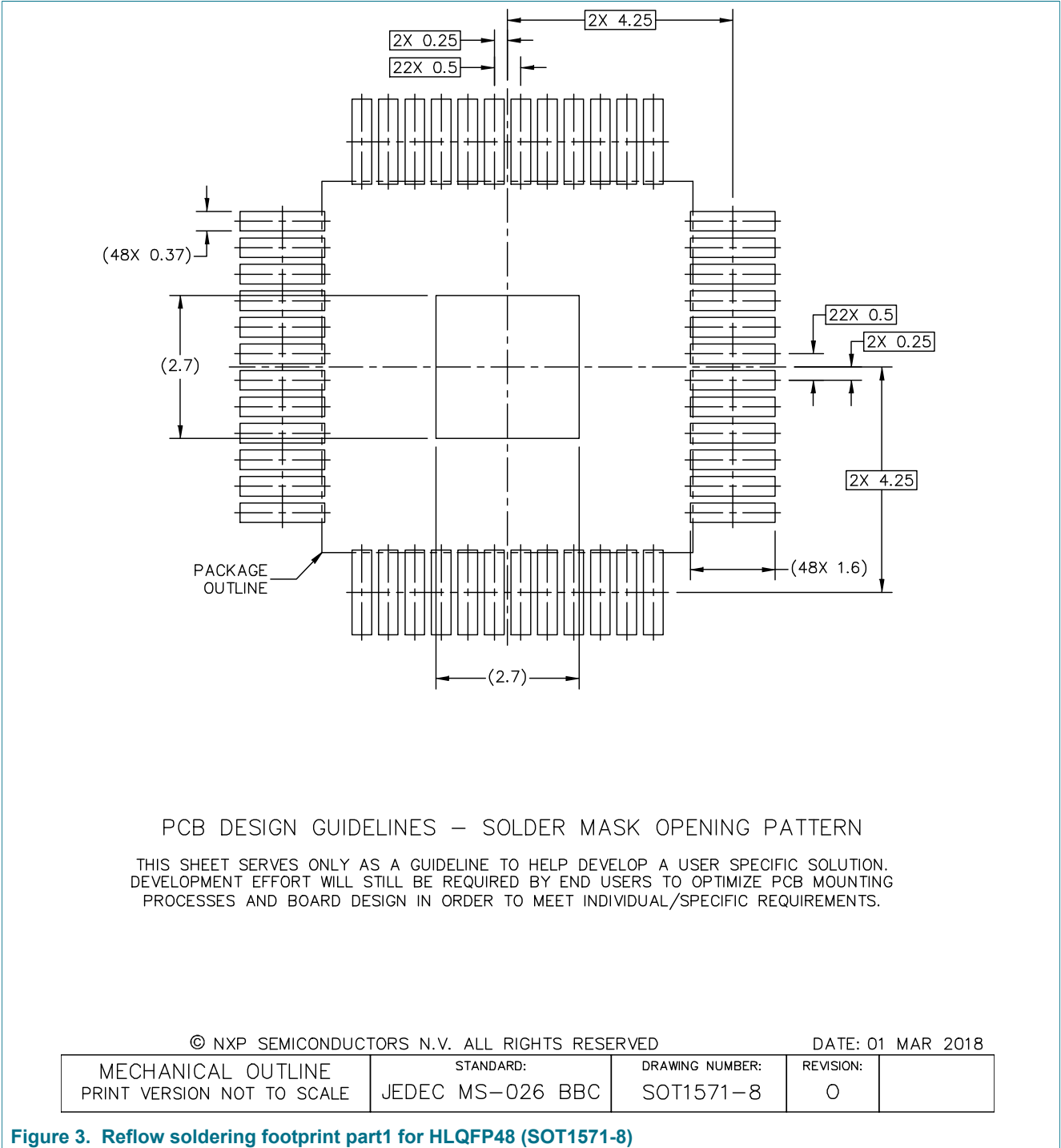
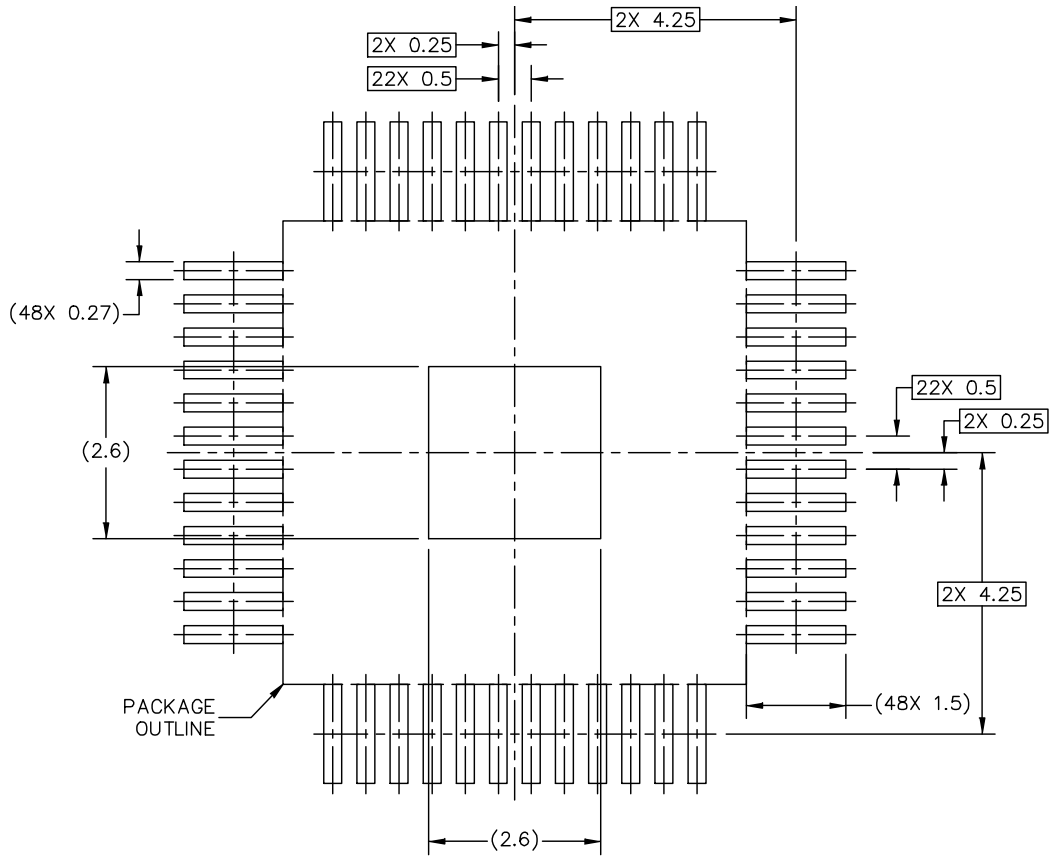


Figure 2. Package outline detail HLQFP48 (SOT1571-8)

3 Soldering



HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 4. Reflow soldering footprint part2 for HLQFP48 (SOT1571-8)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

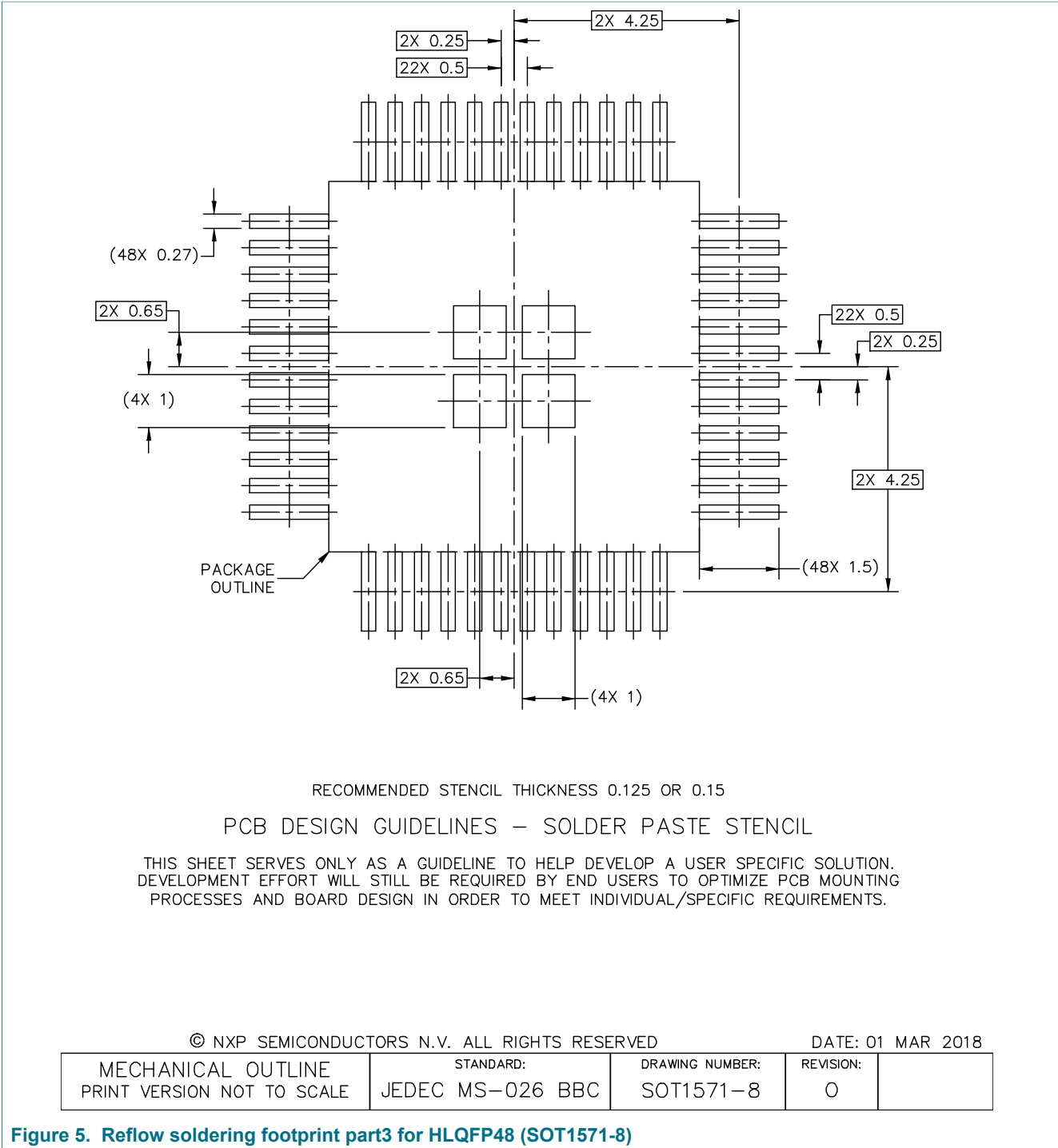


Figure 5. Reflow soldering footprint part3 for HLQFP48 (SOT1571-8)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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Figure 6. Package outline note HLQFP48 (SOT1571-8)

4 Legal information

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